/ Descriptions

WR0<50P ṂṂÞ SQS ÆṀч s Ⅱㄱ Silicon PNP transistor in a TO-92LM Plastic Package.

/ a8dc8atures

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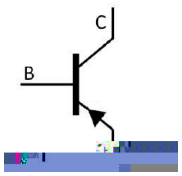
Excellent high current linearity, low saturation voltage.

/ aApplicationsa8dc0

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High frequency low power amplifier applications.

/ a8dc8Equivalent Circuit



/ 05 d c 0 Pinning



PIN1 χ Base PIN 2 χ Collector PIN 3 χ Emitter

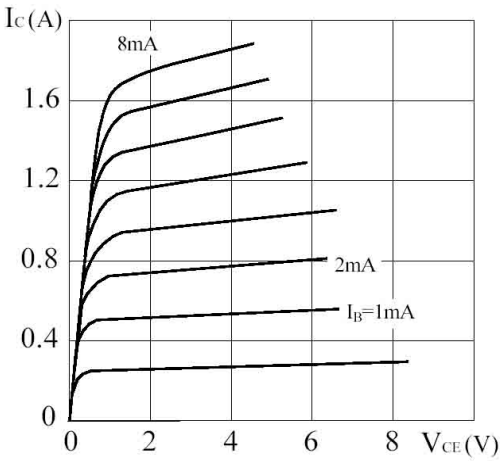
/ h_{FE} Classifications & Marking

h_{FE}

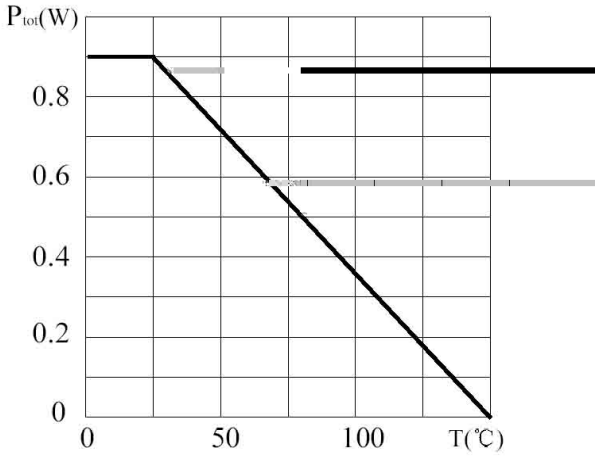
v ̈Ọ	ϒ N	̈Ọ Ө
Parameter	Symbol	

/ Electrical Characteristic Curve

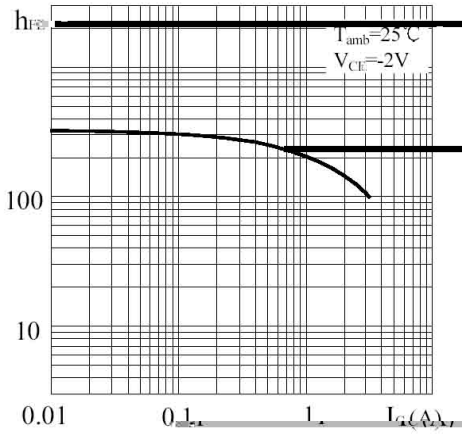
I_C-V_{CE}



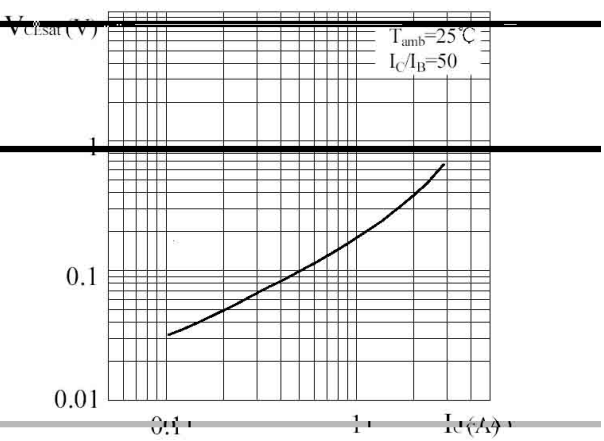
P_{tot}-T_{amb}



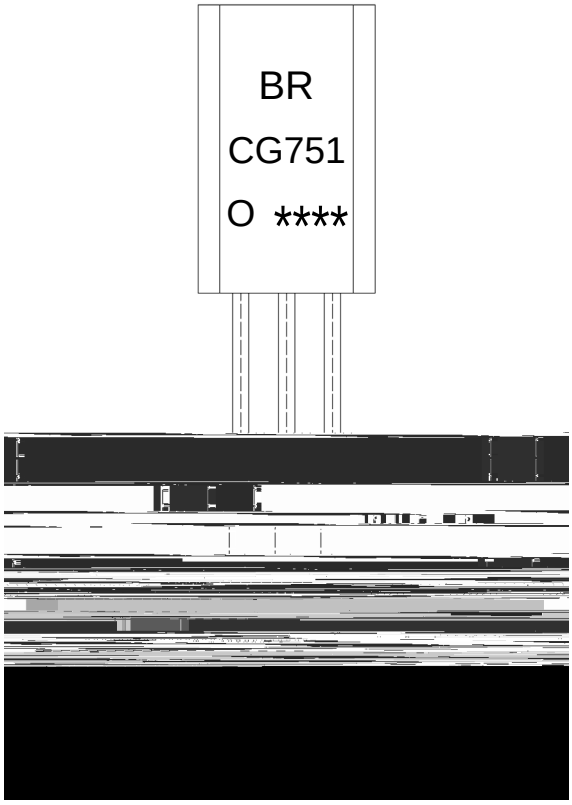
h_{FE}-I_C



V_{CEsat}-I_C

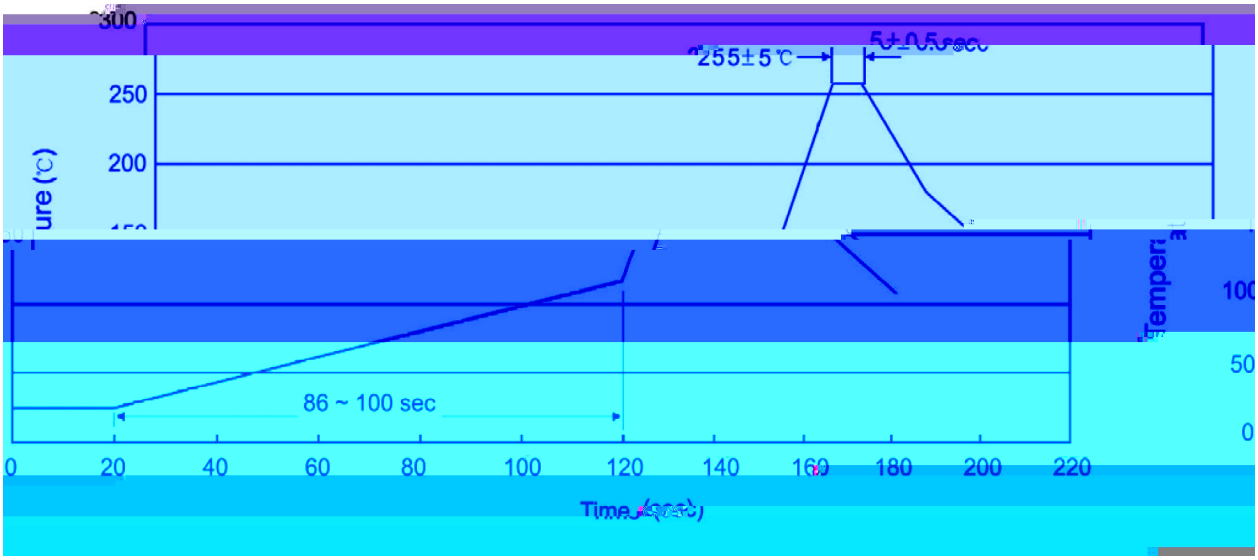


/ Marking Instructions



ب ″ χ	
EU=	ѭ ҙ и Ґђ
FJ : 84 χ	ѭ ҙ N Ґђ
R=	ѭ k IH ‘ 6 Ґђ
---- χ	ѭ ł ғ ӈ̋ N Ґђ ı ₺ ł ғ ӈ̋ N Ψ ק
Note:	
BR:	Company Code.
CG751:	Product Type.
O:	h_{FE} Classifications Symbol
****:	Lot No. Code,code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)



ب ˝ χ

1 Ĺ ♬ □ ỷ 25 Ḱ 150 ł ı `H ڑ 60 Ḱ 90sec;

2 Š Ë □ ỷ 255 ° 5 ł ı `H ڑ `Y ﾊ ㎞ 5 ° 0.5sec;

3 ì ˙ Ⅵ ˛ ɔ ﻉ ỷ ㎞ 2 Ḱ 10 ł /sec.

Note:

1.Preheating:25~150 ł , Time:60~90sec.

2.Peak Temp.:255 ° 5 ł , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ł /sec.

/ Resistance to Soldering Heat Test Conditions

□ ỷ χ 270 ° 5 ł `H ڑ χ 10 ° 1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

¨Ω ţ ﾔ Ł / BULK

Package Type	Units					Dimension			(unit mm3)
	Units/Bag /	Bags/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Bag	ﻩ)	ﻩ)	ﻩ)